

74ALVT16823

18-bit bus-interface D-type flip-flop with reset and enable;
3-state

Rev. 5 — 22 January 2018

Product data sheet

1 General description

The 74ALVT16823 18-bit bus interface register is designed to eliminate the extra packages required to buffer existing registers and provide extra data width for wider data/address paths of buses carrying parity.

The 74ALVT16823 has two 9-bit wide buffered registers with clock enable (pin \overline{nCE}) and master reset (pin \overline{nMR}) which are ideal for parity bus interfacing in high microprogrammed systems.

The registers are fully edge-triggered. The state of each D input, one set-up time before the LOW-to-HIGH clock transition is transferred to the corresponding Q output of the flip-flop.

It is designed for V_{CC} operation from 2.5 V to 3.0 V with I/O compatibility to 5 V.

2 Features and benefits

- Two sets of high speed parallel registers with positive edge-triggered D-type flip-flops
- 5 V I/O compatible
- Ideal where high speed, light loading, or increased fan-in are required with MOS microprocessors
- Bus hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion and extraction permitted
- Power-up 3-state
- Power-up reset
- No bus current loading when output is tied to 5 V bus
- Output capability: +64 mA to -32 mA
- Latch-up protection:
 - JESD78: exceeds 500 mA
- ESD protection:
 - MIL STD 883, method 3 015: exceeds 2000 V
 - MM: exceeds 200 V

3 Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74ALVT16823DL	-40 °C to +85 °C	SSOP56	plastic shrink small outline package; 56 leads; body width 7.5 mm	SOT371-1
74ALVT16823DGG	-40 °C to +85 °C	TSSOP56	plastic thin shrink small outline package; 56 leads; body width 6.1 mm	SOT364-1

4 Functional diagram

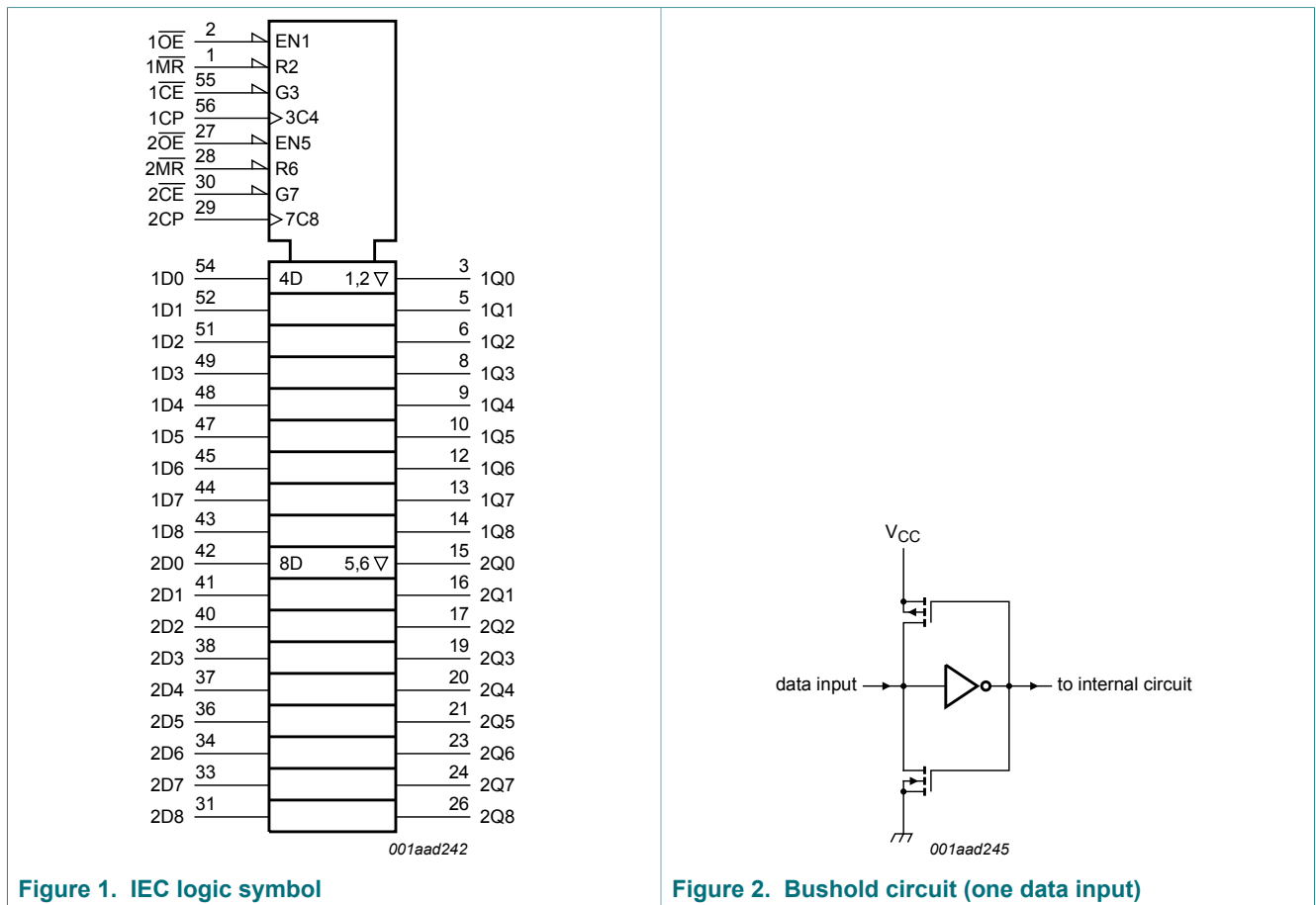


Figure 1. IEC logic symbol

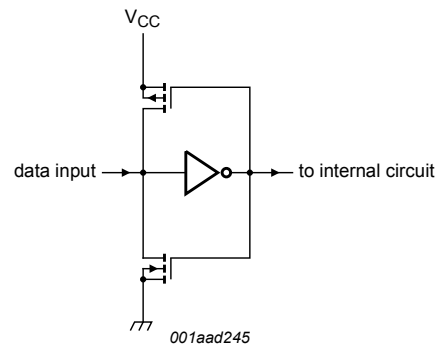


Figure 2. Bushold circuit (one data input)

18-bit bus-interface D-type flip-flop with reset and enable; 3-state

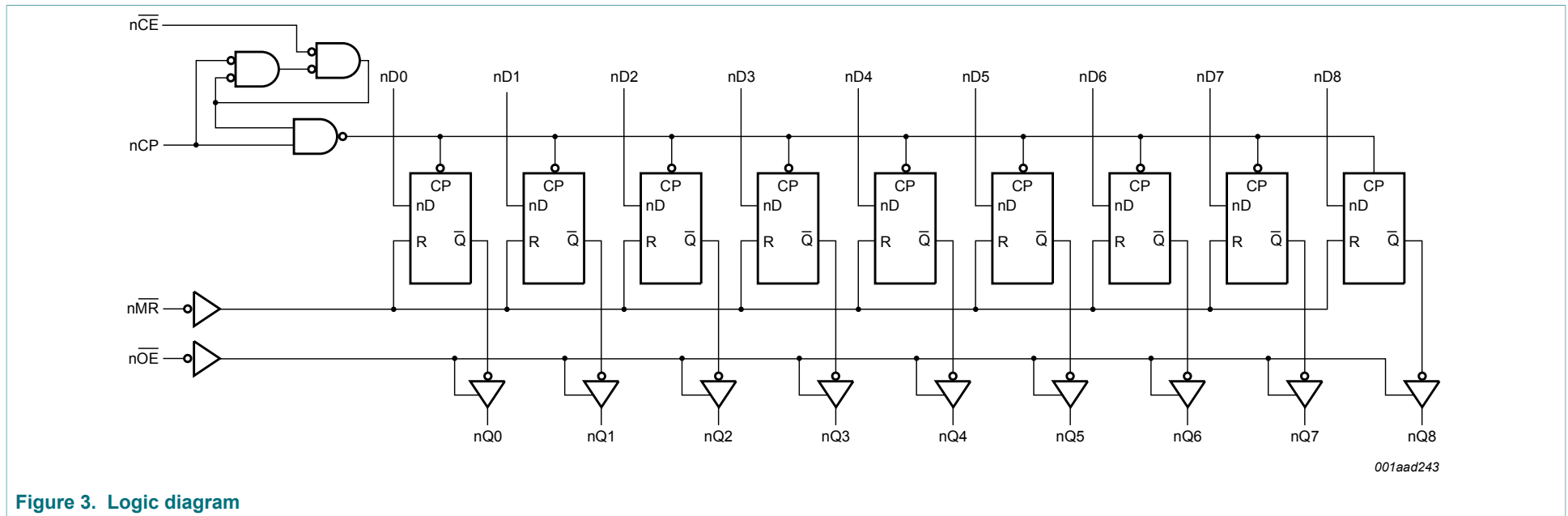
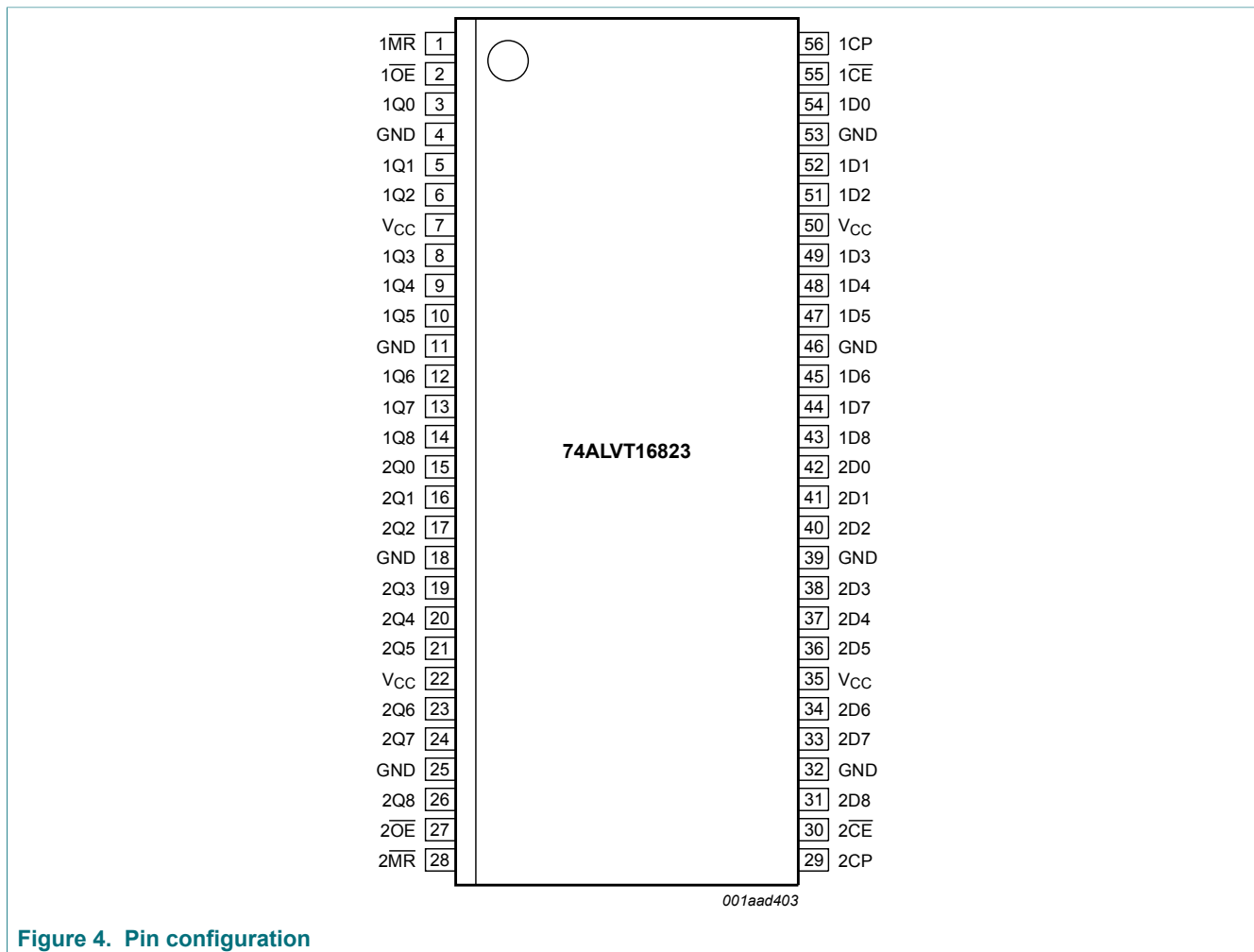


Figure 3. Logic diagram

5 Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7, 1D8	54, 52, 51, 49, 48, 47, 45, 44, 43	data inputs
1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7, 1Q8	3, 5, 6, 8, 9, 10, 12, 13, 14	data outputs
2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7, 2D8	42, 41, 40, 38, 37, 36, 34, 33, 31	data inputs
2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7, 2Q8	15, 16, 17, 19, 20, 21, 23, 24, 26	data outputs
1 $\overline{\text{MR}}$, 2 $\overline{\text{MR}}$	1, 28	master reset input (active-LOW)
1 $\overline{\text{OE}}$, 2 $\overline{\text{OE}}$	2, 27	output enable inputs (active LOW)
1CP, 2CP	56, 29	clock pulse inputs (active rising edge)
1 $\overline{\text{CE}}$, 2 $\overline{\text{CE}}$	55, 30	clock enable input (active-LOW)
GND	4, 11, 18, 25, 32, 39, 46, 53	ground (0 V)
V _{CC}	7, 22, 35, 50	supply voltage

6 Functional description

Table 3. Function table ^[1]

Operating mode	Input					Output
	n $\overline{\text{OE}}$	n $\overline{\text{MR}}$	n $\overline{\text{CE}}$	nCP	nDn	nQn
clear	L	L	X	X	X	L
load and read data	L	H	L	\uparrow	h	H
					l	L
hold	L	H	H	$\overline{\uparrow}$	X	NC
high-impedance	H	X	X	X	X	Z

- [1] H = HIGH voltage level;
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition;
 L = LOW voltage level;
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;
 NC = no change;
 X = don't care;
 Z = high-impedance OFF-state;
 \uparrow = LOW-to-HIGH clock transition;
 $\overline{\uparrow}$ = not a LOW-to-HIGH clock transition.

7 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
V_I	input voltage		[1] -0.5	+7.0	V
V_O	output voltage	output in OFF-state or HIGH-state	[1] -0.5	+7.0	V
I_{IK}	input clamping current	$V_I < 0$ V	-	-50	mA
I_{OK}	output clamping current	$V_O < 0$ V	-	-50	mA
I_O	output current	output in LOW-state	-	128	mA
		output in HIGH-state	-64	-	mA
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		[2] -	150	°C

[1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

8 Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC} = 2.5$ V						
V_{CC}	supply voltage		2.3	-	2.7	V
V_I	input voltage		0	-	5.5	V
I_{OH}	HIGH-level output current		-	-	-8	mA
I_{OL}	LOW-level output current	none	-	-	8	mA
		current duty cycle ≤ 50 %; $f \geq 1$ kHz	-	-	24	mA
$\Delta t/\Delta v$	input transition rise or fall rate	outputs enabled	-	-	10	ns/V
T_{amb}	ambient temperature	in free air	-40	-	+85	°C
$V_{CC} = 3.3$ V						
V_{CC}	supply voltage		3.0	-	3.6	V
V_I	input voltage		0	-	5.5	V
I_{OH}	HIGH-level output current		-	-	-32	mA
I_{OL}	LOW-level output current	none	-	-	32	mA
		current duty cycle ≤ 50 %; $f \geq 1$ kHz	-	-	64	mA
$\Delta t/\Delta v$	input transition rise or fall rate	outputs enabled	-	-	10	ns/V
T_{amb}	ambient temperature	in free air	-40	-	+85	°C

9 Static characteristics

Table 6. Static characteristics

At recommended operating conditions; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$						
V_{IK}	input clamping voltage	$V_{CC} = 2.3\text{ V}$; $I_{IK} = -18\text{ mA}$	-	-0.85	-1.2	V
V_{IH}	HIGH-level input voltage		1.7	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.7	V
V_{OH}	HIGH-level output voltage	$V_{CC} = 2.3\text{ V}$ to 2.7 V ; $I_O = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$	V_{CC}	-	V
		$V_{CC} = 2.3\text{ V}$; $I_O = -8\text{ mA}$	1.8	2.5	-	V
V_{OL}	LOW-level output voltage	$V_{CC} = 2.3\text{ V}$; $I_O = 100\text{ }\mu\text{A}$	-	0.07	0.2	V
		$V_{CC} = 2.3\text{ V}$; $I_O = 24\text{ mA}$	-	0.3	0.5	V
		$V_{CC} = 2.3\text{ V}$; $I_O = 8\text{ mA}$	-	-	0.4	V
$V_{OL(pu)}$	power-up LOW-level output voltage	$V_{CC} = 2.7\text{ V}$; $I_O = 1\text{ mA}$; $V_I = V_{CC}$ or GND ^[2]	-	-	0.55	V
I_I	input leakage current	control pins				
		$V_{CC} = 2.7\text{ V}$; $V_I = V_{CC}$ or GND	-	0.1	± 1	μA
		$V_{CC} = 0\text{ V}$ to 2.7 V ; $V_I = 5.5\text{ V}$	-	0.1	10	μA
		I/O data pins ^[3]				
		$V_{CC} = 2.7\text{ V}$; $V_I = V_{CC}$	-	0.1	1	μA
	$V_{CC} = 2.7\text{ V}$; $V_I = 0\text{ V}$	-	+0.1	-5	μA	
I_{OFF}	power-off leakage current	$V_{CC} = 0\text{ V}$; V_I or $V_O = 0\text{ V}$ to 4.5 V	-	+0.1	± 100	μA
I_{BHL}	bus hold LOW current	data inputs; $V_{CC} = 2.3\text{ V}$; $V_I = 0.7\text{ V}$ ^[4]	-	100	-	μA
I_{BHH}	bus hold HIGH current	data inputs; $V_{CC} = 2.3\text{ V}$; $V_I = 1.7\text{ V}$ ^[4]	-	-70	-	μA
I_{EX}	external current	output HIGH-state when $V_O > V_{CC}$; $V_O = 5.5\text{ V}$; $V_{CC} = 2.3\text{ V}$	-	10	125	μA
$I_{O(pu/pd)}$	power-up/power-down output current	$V_{CC} \leq 1.2\text{ V}$; $V_O = 0.5\text{ V}$ to V_{CC} ; $V_I = \text{GND}$ or V_{CC} ^[5]	-	1	± 100	μA
I_{OZ}	OFF-state output current	$V_{CC} = 2.7\text{ V}$; $V_I = V_{IL}$ or V_{IH}				
		output HIGH state; $V_O = 2.3\text{ V}$	-	0.5	5	μA
		output LOW-state; $V_O = 0.5\text{ V}$	-	+0.5	-5	μA
I_{CC}	supply current	$V_{CC} = 2.7\text{ V}$; $V_I = \text{GND}$ or V_{CC} ; $I_O = 0\text{ A}$				
		outputs HIGH-state	-	0.04	0.1	mA
		outputs LOW-state	-	2.7	4.5	mA
		outputs disabled ^[6]	-	0.04	0.1	mA
ΔI_{CC}	additional supply current	per input pin; $V_{CC} = 2.3\text{ V}$ to 2.7 V ; one input at $V_{CC} - 0.6\text{ V}$, other inputs at V_{CC} or GND ^[7]	-	0.04	0.4	mA
C_I	input capacitance	$V_I = 0\text{ V}$ or V_{CC}	-	3	-	pF
C_O	output capacitance	$V_{IO} = 0\text{ V}$ or 3.0 V	-	9	-	pF

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{CC} = 3.3 V ± 0.3 V						
V _{IK}	input clamping voltage	V _{CC} = 3.0 V; I _{IK} = -18 mA	-	-0.85	-1.2	V
V _{IH}	HIGH-level input voltage		2.0	-	-	V
V _{IL}	LOW-level input voltage		-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _{CC} = 3.0 V to 3.6 V; I _O = -100 μA	V _{CC} - 0.2	V _{CC}	-	V
		V _{CC} = 3.0 V; I _O = -32 mA	2.0	2.3	-	V
V _{OL}	LOW-level output voltage	V _{CC} = 3.0 V; I _O = 100 μA	-	0.07	0.2	V
		V _{CC} = 3.0 V; I _O = 16 mA	-	0.25	0.4	V
		V _{CC} = 3.0 V; I _O = 32 mA	-	0.3	0.5	V
		V _{CC} = 3.0 V; I _O = 64 mA	-	0.4	0.55	V
V _{OL(pu)}	power-up LOW-level output voltage	V _{CC} = 3.6 V; I _O = 1 mA; V _I = V _{CC} or GND ^[2]	-	-	0.55	V
I _I	input leakage current	control pins				
		V _{CC} = 3.6 V; V _I = V _{CC} or GND	-	0.1	±1	μA
		V _{CC} = 0 V or 3.6 V; V _I = 5.5 V	-	0.1	10	μA
		I/O data pins ^[3]				
		V _{CC} = 3.6 V; V _I = V _{CC}	-	0.5	1	μA
		V _{CC} = 3.6 V; V _I = 0 V	-	+0.1	-5	μA
I _{OFF}	power-off leakage current	V _{CC} = 0 V; V _I or V _O = 0 V to 4.5 V	-	0.1	±100	μA
I _{BHL}	bus hold LOW current	data inputs; V _{CC} = 3 V; V _I = 0.8 V	75	130	-	μA
I _{BHH}	bus hold HIGH current	data inputs; V _{CC} = 3 V; V _I = 2.0 V	-75	-140	-	μA
I _{BHLO}	bus hold LOW overdrive current	data inputs; V _{CC} = 3.6 V; V _I = 0 V to 3.6 V ^[8]	500	-	-	μA
I _{BHHO}	bus hold HIGH overdrive current	data inputs; V _{CC} = 3.6 V; V _I = 0 V to 3.6 V ^[8]	-500	-	-	μA
I _{EX}	external current	output HIGH-state when V _O > V _{CC} ; V _O = 5.5 V; V _{CC} = 3.0 V	-	10	125	μA
I _{O(pu/pd)}	power-up/power-down output current	V _{CC} ≤ 1.2 V; V _O = 0.5 V to V _{CC} ; V _I = GND or V _{CC} ^[9]	-	1	±100	μA
I _{OZ}	OFF-state output current	V _{CC} = 3.6 V; V _I = V _{IL} or V _{IH}				
		output HIGH state; V _O = 3.0 V	-	0.5	5	μA
		output LOW-state; V _O = 0.5 V	-	+0.5	-5	μA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = GND or V _{CC} ; I _O = 0 A				
		outputs HIGH-state	-	0.06	0.1	mA
		outputs LOW-state	-	3.9	5.5	mA
		outputs disabled ^[6]	-	0.06	0.1	mA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 3 V to 3.6 V; one input at V _{CC} - 0.6 V, other inputs at V _{CC} or GND ^[7]	-	0.04	0.4	mA

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
C _I	input capacitance	V _I = 0 V or V _{CC}	-	3	-	pF
C _O	output capacitance	V _{I/O} = 0 V or 3.0 V	-	9	-	pF

- [1] All typical values for V_{CC} = 2.5 V ± 0.2 V are measured at V_{CC} = 2.5 V and T_{amb} = 25 °C.
All typical values for V_{CC} = 3.3 V ± 0.3 V are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.
- [2] For valid test results, data must not be loaded into the flip-flops after applying power.
- [3] Unused pins at V_{CC} or GND.
- [4] Not guaranteed.
- [5] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms. From V_{CC} = 1.2 V to V_{CC} = 2.5 V ± 0.2 V a transition time of 100 μs is permitted. This parameter is valid for T_{amb} = 25 °C only.
- [6] I_{CC} is measured with outputs pulled up to V_{CC} or pulled down to ground.
- [7] This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.
- [8] This is the bus hold overdrive current required to force the input to the opposite logic state.
- [9] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms. From V_{CC} = 1.2 V to V_{CC} = 3.3 V ± 0.3 V a transition time of 100 μs is permitted. This parameter is valid for T_{amb} = 25 °C only.

10 Dynamic characteristics

Table 7. Dynamic characteristics

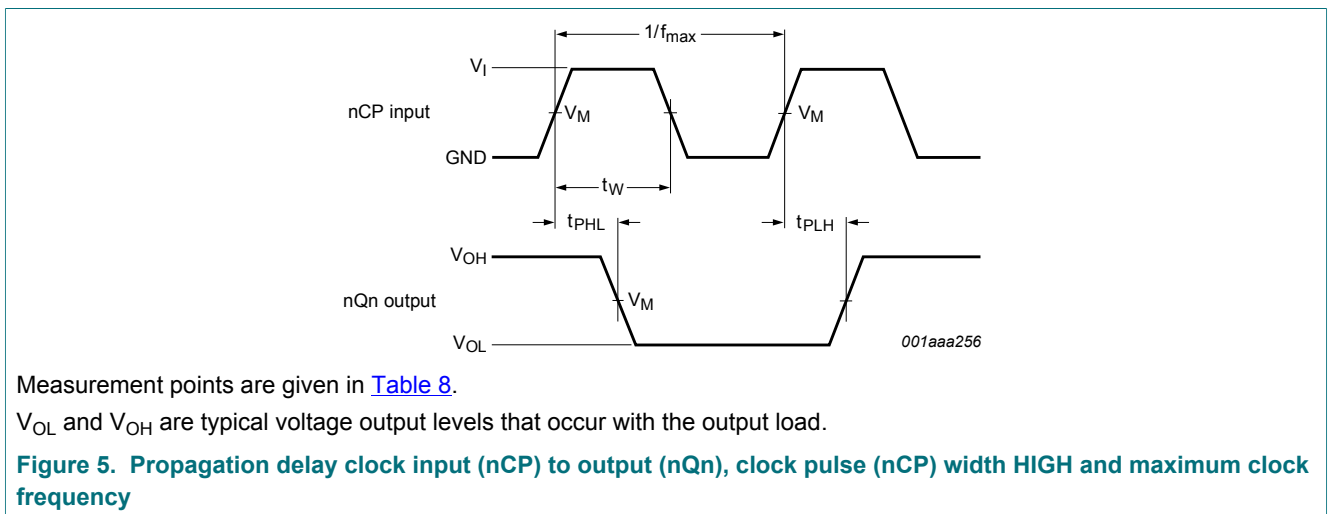
Voltages are referenced to GND (ground = 0 V); T_{amb} = -40 °C to +85 °C; for test circuit see [Figure 9](#).

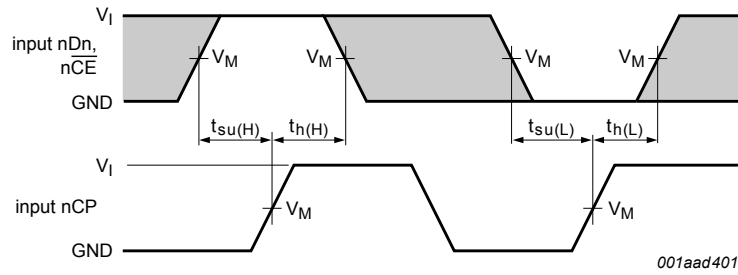
Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{CC} = 2.5 V ± 0.2 V						
t _{PLH}	LOW to HIGH propagation delay	nCP to nQn; see Figure 5	1.5	2.9	4.5	ns
t _{PHL}	HIGH-to-LOW propagation delay	nCP to nQn; see Figure 5	1.4	2.7	4.2	ns
		nMR to nQn; see Figure 7	1.5	2.7	4.2	ns
t _{PZH}	OFF-state to HIGH propagation delay	nOE to nQn; see Figure 8	2.1	3.4	5.0	ns
t _{PZL}	OFF-state to LOW propagation delay	nOE to nQn; see Figure 8	1.8	3.0	4.7	ns
t _{PHZ}	HIGH to OFF-state propagation delay	nOE to nQn; see Figure 8	1.7	3.0	4.3	ns
t _{PLZ}	LOW to OFF-state propagation delay	nOE to nQn; see Figure 8	1.4	2.3	3.3	ns
t _{su(H)}	set-up time HIGH	nDn to nCP; see Figure 6	1.0	0.5	-	ns
		nCE to nCP; see Figure 6	1.0	0.2	-	ns
t _{su(L)}	set-up time LOW	nDn to nCP; see Figure 6	1.8	1.3	-	ns
		nCE to nCP; see Figure 6	0.5	-0.1	-	ns
t _{h(H)}	hold time HIGH	nDn to nCP; see Figure 6	0.1	-1.4	-	ns
		nCE to nCP; see Figure 6	1.0	0.2	-	ns
t _{h(L)}	hold time LOW	nDn to nCP; see Figure 6	0.1	-0.5	-	ns
		nCE to nCP; see Figure 6	1.0	-0.1	-	ns
t _{WH}	pulse width HIGH	nCP; see Figure 5	2.0	0.8	-	ns
t _{WL}	pulse width LOW	nCP	3.0	2.1	-	ns
		nMR; see Figure 7	2.0	0.8	-	ns
t _{rec}	recovery time	nMR to nCP; see Figure 7	2.0	1.3	-	ns
f _{max}	maximum frequency	CP; see Figure 5	150	-	-	MHz

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{CC} = 3.3 V ± 0.3 V						
t _{PLH}	LOW to HIGH propagation delay	nCP to nQn; see Figure 5	1.0	2.3	3.1	ns
t _{PHL}	HIGH-to-LOW propagation delay	nCP to nQn; see Figure 5	1.0	2.1	2.9	ns
		nMR to nQn; see Figure 7	1.0	2.3	2.9	ns
t _{PZH}	OFF-state to HIGH propagation delay	nOE to nQn; see Figure 8	1.7	2.7	4.0	ns
t _{PZL}	OFF-state to LOW propagation delay	nOE to nQn; see Figure 8	1.4	2.3	3.5	ns
t _{PHZ}	HIGH to OFF-state propagation delay	nOE to nQn; see Figure 8	2.2	3.1	4.0	ns
t _{PLZ}	LOW to OFF-state propagation delay	nOE to nQn; see Figure 8	1.8	2.6	3.5	ns
t _{su(H)}	set-up time HIGH	nDn to nCP; see Figure 6	1.0	0.5	-	ns
		nCE to nCP; see Figure 6	1.0	0.1	-	ns
t _{su(L)}	set-up time LOW	nDn to nCP; see Figure 6	1.6	1.1	-	ns
		nCE to nCP; see Figure 6	0.5	-0.5	-	ns
t _{h(H)}	hold time HIGH	nDn to nCP; see Figure 6	0.1	-0.7	-	ns
		nCE to nCP; see Figure 6	1.0	0.5	-	ns
t _{h(L)}	hold time LOW	nDn to nCP; see Figure 6	0.1	-0.5	-	ns
		nCE to nCP; see Figure 6	1.0	-0.1	-	ns
t _{WH}	pulse width HIGH	nCP; see Figure 5	1.5	0.7	-	ns
t _{WL}	pulse width LOW	nCP	2.5	1.4	-	ns
		nMR; see Figure 7	2.0	1.5	-	ns
t _{rec}	recovery time	nMR to nCP; see Figure 7	2.0	1.1	-	ns
f _{max}	maximum frequency	CP; see Figure 5	250	-	-	MHz

[1] All typical values for V_{CC} = 2.5 V ± 0.2 V are measured at V_{CC} = 2.5 V and T_{amb} = 25 °C.
 All typical values for V_{CC} = 3.3 V ± 0.3 V are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

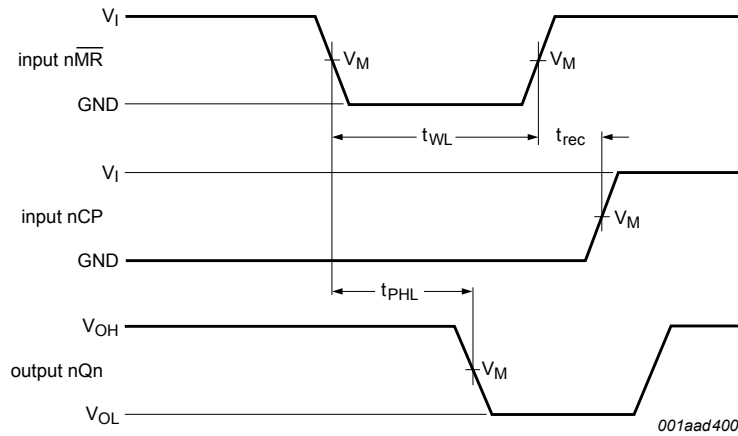
10.1 Waveforms and test circuit





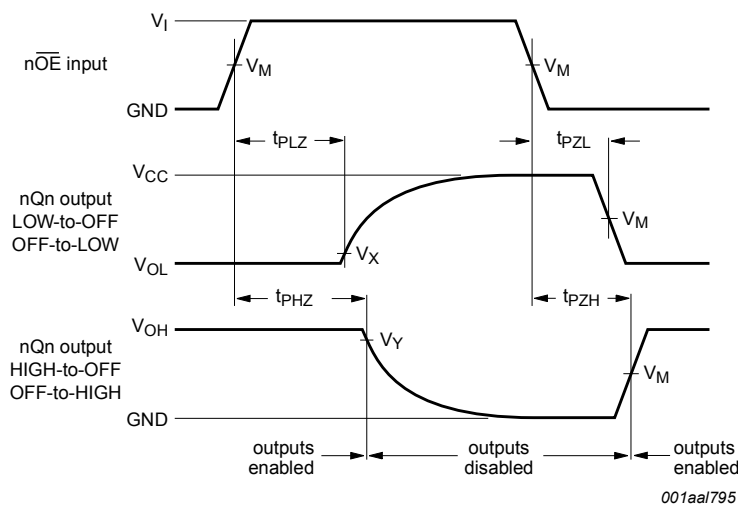
Measurement points are given in [Table 8](#).
The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 6. Data set-up and hold times



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 7. Master reset pulse width, master reset to output delay and master reset to clock recovery time



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 8. OFF-state to HIGH and LOW propagation delays and LOW and HIGH to OFF-state propagation delays

Table 8. Measurement points

V _{CC}	Input	Output		
	V _M	V _M	V _X	V _Y
≤ 2.7 V	0.5 x V _{CC}	0.5 x V _{CC}	V _{OL} + 0.15 V	V _{OH} - 0.15 V
≥ 3.0 V	1.5 V	1.5 V	V _{OL} + 0.3 V	V _{OH} - 0.3 V

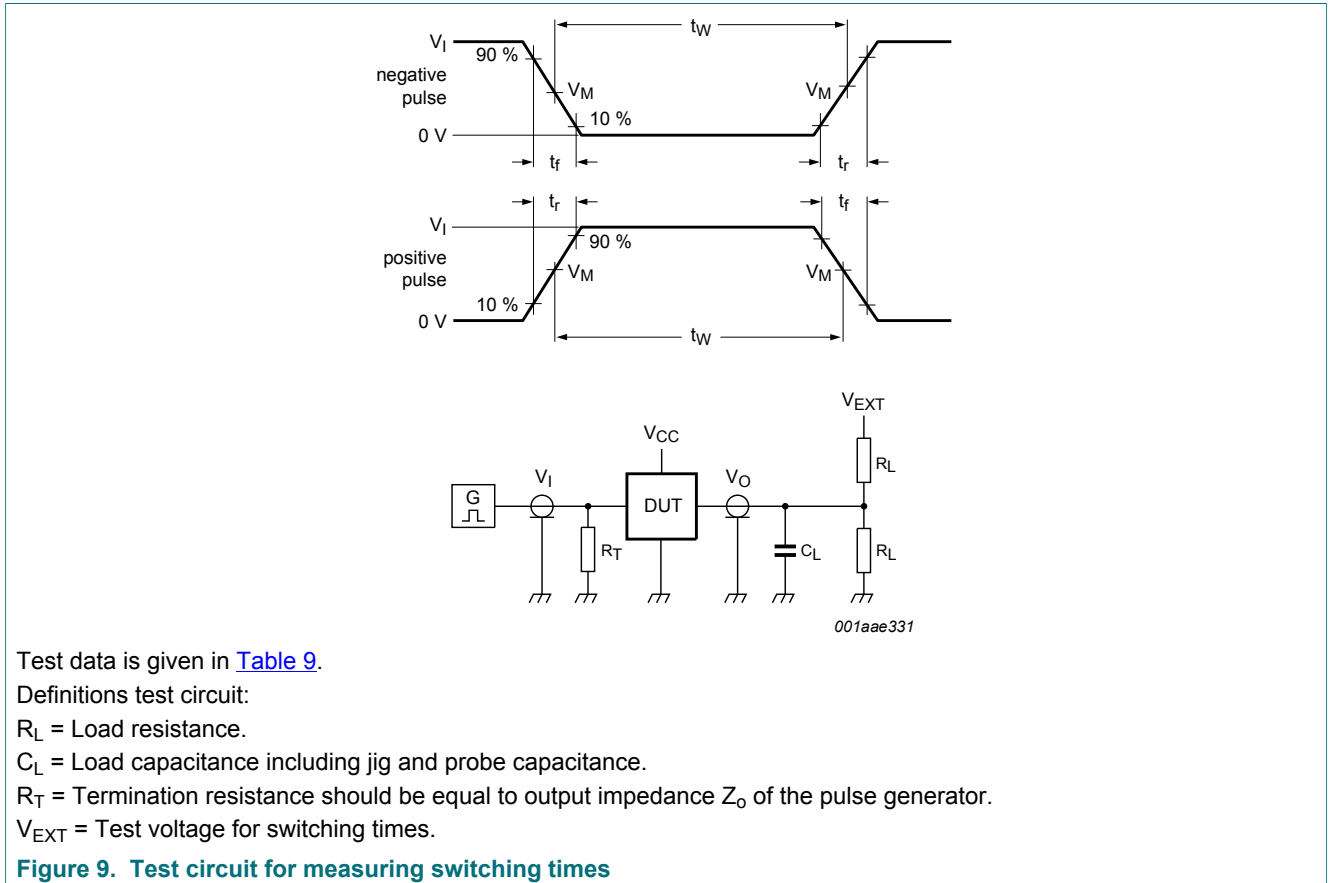


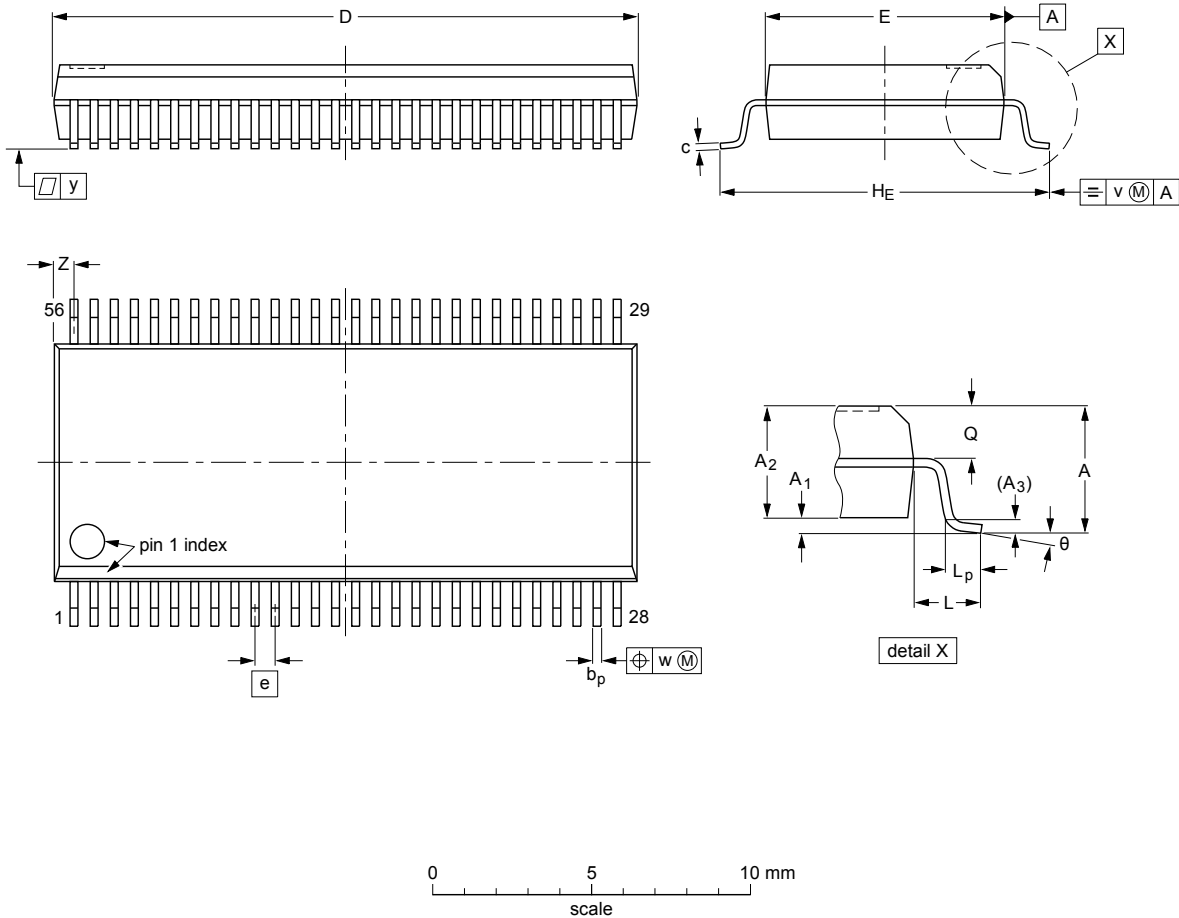
Table 9. Test data

Input			Load			V _{EXT}		
V _I	f _i	t _W	t _r , t _f	C _L	R _L	t _{PHZ} , t _{PZH}	t _{PLZ} , t _{PZL}	t _{PLH} , t _{PHL}
3.0 V or V _{CC} whichever is less	≤ 10 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	GND	6 V or V _{CC} x 2	open

11 Package outline

SSOP56: plastic shrink small outline package; 56 leads; body width 7.5 mm

SOT371-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	18.55 18.30	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

Note

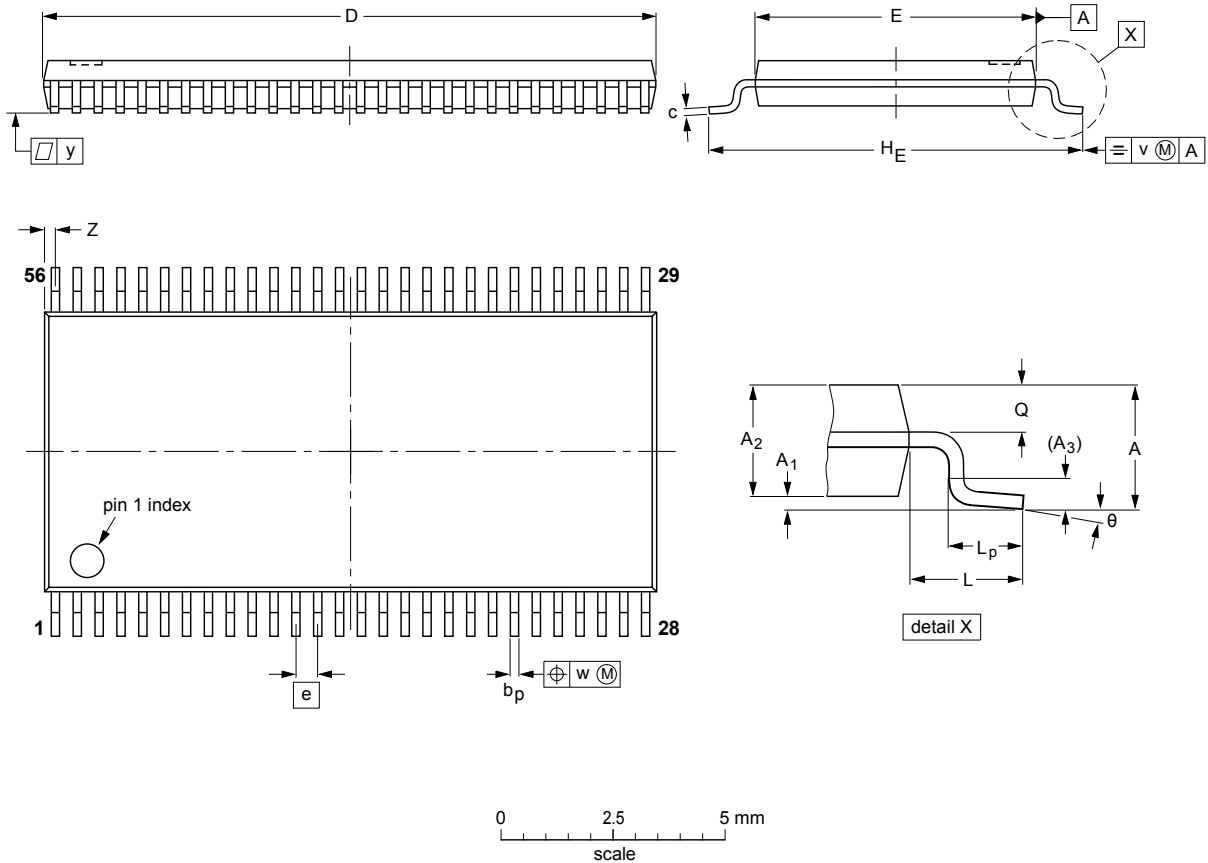
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT371-1		MO-118				99-12-27 03-02-18

Figure 10. Package outline SOT371-1 (SSOP56)

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm

SOT364-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT364-1		MO-153				-99-12-27 03-02-19

Figure 11. Package outline SOT364-1 (TSSOP56)

12 Abbreviations

Table 10. Abbreviations

Acronym	Description
DUT	Device Under Test
ESD	ElectroStatic Discharge
MIL	Military
MM	Machine Model
MOS	Metal-Oxide Semiconductor

13 Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVT16823 v.5	20180122	Product data sheet	-	74ALVT16823 v.4
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. 			
74ALVT16823 v.4	20050802	Product data sheet	-	74ALVT16823 v.3
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors. Section 2: modified 'Jedec Std 17' into 'JESD78' Section 10: changed propagation delays. 			
74ALVT16823 v.3	19980612	Product specification	-	74ALVT16823 v.2
74ALVT16823 v.2	19980612	Product specification	-	74ALVT16823 v.1
74ALVT16823 v.1	19980303	Product specification	-	-

14 Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

14.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet.

14.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia. In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory. Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — Nexperia products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical

systems or equipment, nor in applications where failure or malfunction of an Nexperia product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Nexperia and its suppliers accept no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification. Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products. Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — Nexperia products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nexperia.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific Nexperia product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. Nexperia accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications. In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without Nexperia's warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond Nexperia's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies Nexperia for any liability, damages or failed product claims resulting from customer

design and use of the product for automotive applications beyond Nexperia's standard warranty and Nexperia's product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

14.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	2
4	Functional diagram	2
5	Pinning information	4
5.1	Pinning	4
5.2	Pin description	5
6	Functional description	5
7	Limiting values	6
8	Recommended operating conditions	6
9	Static characteristics	7
10	Dynamic characteristics	9
10.1	Waveforms and test circuit	10
11	Package outline	13
12	Abbreviations	15
13	Revision history	15
14	Legal information	16

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© Nexperia B.V. 2018.

All rights reserved.

For more information, please visit: <http://www.nexperia.com>

For sales office addresses, please send an email to: salesaddresses@nexperia.com

Date of release: 22 January 2018
Document identifier: 74ALVT16823

Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели,
кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



Телефон: 8 (812) 309-75-97 (многоканальный)

Факс: 8 (812) 320-03-32

Электронная почта: ocean@oceanchips.ru

Web: <http://oceanchips.ru/>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А